

AMENDMENT TO THE CLAIMS

Claims 1-18 (Cancelled)

19.(Original) A manufacturing process of a packaged component, comprising:

- (a) preparing an element;
- (b) depositing a volume-changing member on at least a partial surface of said prepared element;
- (c) sealing said element and said volume-changing member with a sealing material;
- (d) shrinking said volume-changing member sealed with said sealing material to release said volume-changing member from the partial surface of said element opposing thereto, thereby to define a space therebetween.

20.(Original) The process according to Claim 19,

wherein said volume-changing member is made of material that shrinks when heated; and

wherein the step (d) is made by heating to shrink said volume-changing member.

21.(Original) The process according to Claim 19,

wherein said volume-changing member is made of material that expands when heated;

wherein the step (c) is made while said volume-changing member is heated for expansion; and

wherein the step (d) is made by cooling to shrink said volume-changing member heated in the step (c).

22.(Original) The process according to Claim 19,

wherein said volume-changing member is made of material that shrinks when exposed to a electromagnetic wave; and

wherein the step (d) is made by radiating the electromagnetic wave to said volume-changing member.

23.(Original) The process according to Claim 19,

the step (b) including,

applying a releasing agent between said volume-changing member and the partial surface of said element opposing thereto,

applying said volume-changing member on said releasing agent, and

applying an adhesive between said volume-changing member and said sealing material opposing thereto.

24.(Original) A manufacturing process of a packaged component, comprising:

(a) preparing an element;

(b) forming a cover layer on at least a partial surface of said prepared element;

(c) depositing a volume-changing member on said cover layer;

(d) sealing said element, said cover layer, and said volume-changing member with a sealing material;

(e) shrinking said volume-changing member sealed with said sealing material to release said volume-changing member from the partial surface of said element opposing thereto, thereby to define a space therebetween.

25.(Original) A manufacturing process of a packaged component, comprising:

(a) preparing a semiconductor integrated circuit chip and a piezoelectric material chip;

(b) arranging said semiconductor integrated circuit chip and said piezoelectric material chip at predetermined positions;

- (c) electrically connecting said semiconductor integrated circuit chip and said piezoelectric material chip to external connection terminals;
- (d) depositing a volume-changing member on at least a partial surface of said piezoelectric material chip;
- (e) sealing said semiconductor integrated circuit chip and said piezoelectric material chip with a sealing material after the steps (c) and (d); and
- (f) shrinking said volume-changing member sealed with said sealing material to define a space between said volume-changing member and the partial surface of said piezoelectric material chip.

26.(Original) A manufacturing process of a packaged component, comprising:

- (a) preparing a first element;
- (b) providing a second element on a surface of said first element;
- (c) depositing a volume-changing member on said second element;
- (d) sealing said first and second elements and said volume-changing member with a sealing material; and
- (e) shrinking said volume-changing member to release said second element from said first element.